

# EDITORIAL CALENDAR

FEB / MAR		APR / MAY		JUN / JUL	
Issue date: Mar 8    Booking: Feb 23 Materials: Mar 1    Editorial: Feb 20		Issue date: Apr 18    Booking: Apr 4 Materials: Apr 11    Editorial: Mar 26		Issue date: Jun 11    Booking: May 27 Materials: Jun 3    Editorial: May 15	
<b>Cover Story</b>	Lithography and Patterning	Silicon Photonics		3D Integration/ Heterogeneous Integration	
<b>Tech Features</b>	Advanced Packaging	Metrology /Analysis /Testing		Advanced Process Equipment / Advanced Process Control	
<b>Column</b>	Materials /Chemicals /Gases	MEMS / Sensors		IC Design Tool/Software /Platform	
<b>Special Supplements</b>	AI and Machine Learning	Power Electronics		IP, Chiplet, SoC, SiP, PoP.....	

AUG / SEP		OCT / NOV		DEC / JAN	
Issue date: Aug 20    Booking: Aug 5 Materials: Aug 12    Editorial: Jul 25		Issue date: Oct 25    Booking: Oct 11 Materials: Oct 18    Editorial: Sep 27		Issue date: Dec 23    Booking: Dec 9 Materials: Dec 16    Editorial: Dec 2	
<b>Cover Story</b>	Wafer Processing	Deposition / Etch / Cleaning		Packaging / Assembly	
<b>Tech Features</b>	Smart Manufacturing / Data Tools / MES	CMP / Post CMP Cleaning		Chiplet Stacks / STCO	
<b>Column</b>	Interconnection/ RDL / TSV	Process Integration		AI and IC Manufacturing	
<b>Special Supplements</b>	Memory Technology	Automotive Semiconductor		Supply Chain / Sustainability	

## Bonus Distribution

### FEB / MAR

- SEMICON China, Shanghai Mar 20-22
- Productronica China, Shanghai, Mar 22-24
- EDICON Beijing, Apr

### APR / MAY

- Nepcon China/ EMT China Shanghai, Apr 24-26
- Chip China/CS China, SuZhou, May

### JUN / JUL



- STCon, Suzhou, Jun

### AUG / SEP

- CIOE, Shenzhen Sep
- Chip China/CS China, Tai Cang, Oct

### OCT / NOV

- Nepcon Asia, Shenzhen, Nov
- Chip China, Xiamen, Nov
- SSL China, Xiamen, Nov
- Productronica S China, Shenzhen, TBA

 	Jan	10	24	Apr	10	24	Jul	10	24	Oct	15	29		
	Feb	6	22	May	14	28	Aug	14	28	20	Nov	12	26	18
	Mar	12	28	15	Jun	12	26	18	Sep	12	26	Dec	12	26

